

# SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

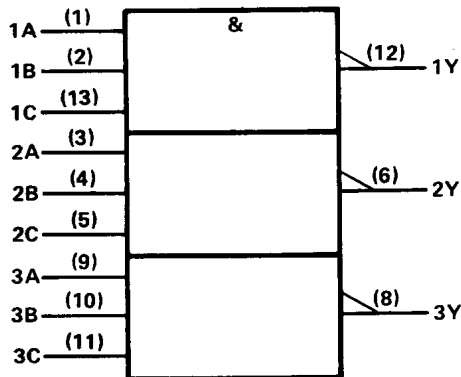
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7410, SN74LS10, and SN74S10 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE (each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

## logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

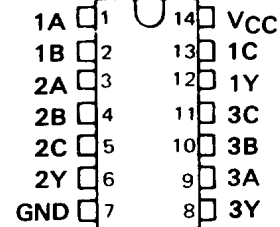
Pin numbers shown are for D, J, and N packages.

## positive logic

$$Y = \overline{A \cdot B \cdot C} \text{ or } Y = \overline{A} + \overline{B} + \overline{C}$$

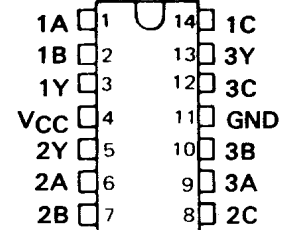
SN5410 . . . J PACKAGE  
SN54LS10, SN54S10 . . . J OR W PACKAGE  
SN7410 . . . N PACKAGE  
SN74LS10, SN74S10 . . . D OR N PACKAGE

(TOP VIEW)



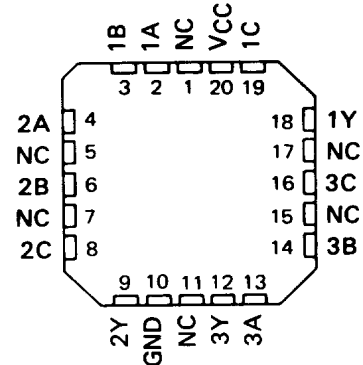
SN5410 . . . W PACKAGE

(TOP VIEW)



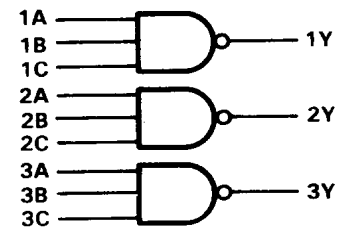
SN54LS10, SN54S10 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

## logic diagram (positive logic)





# SN5410, SN7410, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

	SN5410			SN7410			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-0.4			-0.4	mA
I <sub>OL</sub> Low-level output current			16			16	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN5410			SN7410			UNIT
		MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA			-1.5			-1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -0.4 mA	2.4	3.4		2.4	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V			40			40	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-20		-55	-18		-55	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		3	6		3	6	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		9	16.5		9	16.5	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A, B or C	Y	R <sub>L</sub> = 400 Ω, C <sub>L</sub> = 15 pF		11	22	ns
t <sub>PHL</sub>					7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

# SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

	SN54LS10			SN74LS10			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.7			0.8	V
I <sub>OH</sub> High-level output current			-0.4			-0.4	mA
I <sub>OL</sub> Low-level output current			4			8	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54LS10			SN74LS10			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5			-1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OH</sub> = -0.4 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 4 mA		0.25	0.4			0.4	V
	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 8 mA					0.25	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			20			20	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.4			-0.4	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-20		-100	-20		-100	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		0.6	1.2		0.6	1.2	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		1.8	3.3		1.8	3.3	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A, B or C	Y	R <sub>L</sub> = 2 kΩ,	C <sub>L</sub> = 15 pF		9	15	ns
t <sub>PHL</sub>						10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



# SN54S10, SN74S10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

	SN54S10			SN74S10			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-1			-1	mA
I <sub>OL</sub> Low-level output current			20			20	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54S10			SN74S10			UNIT
		MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 20 mA			0.5			0.5	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50			50	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V			-2			-2	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
I <sub>CC</sub> H	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		7.5	12		7.5	12	mA
I <sub>CC</sub> L	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		15	27		15	27	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A, B or C	Y	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF		3	4.5	ns
t <sub>PHL</sub>					3	5	ns
t <sub>PLH</sub>			R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 50 pF		4.5		ns
t <sub>PHL</sub>					5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/00103BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/00103BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5410J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7410N	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7410N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7410NE4	NRND	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS10NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S10N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S10NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ5410J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5410W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ5410WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

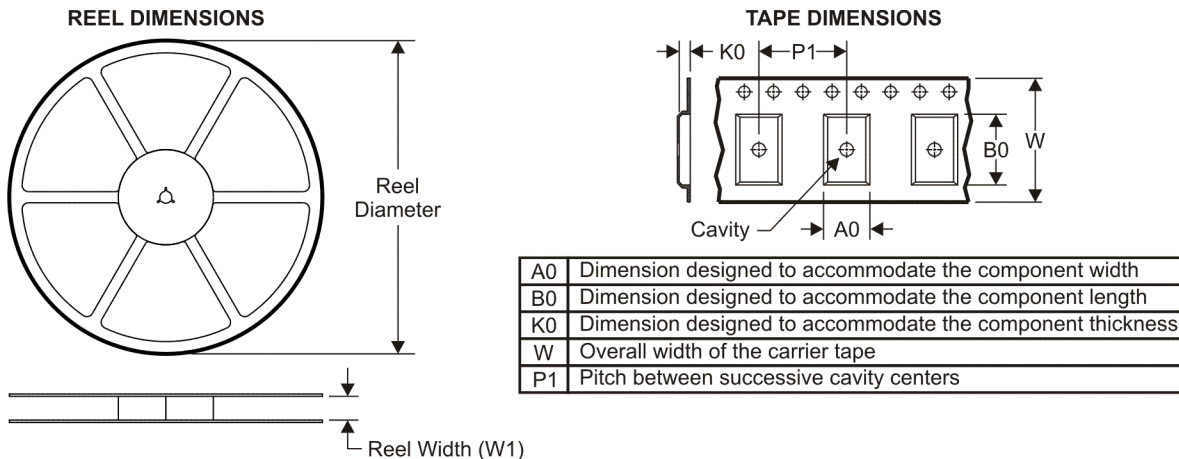
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

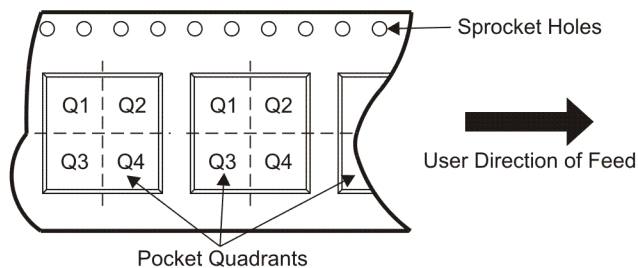
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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS10DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS10NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

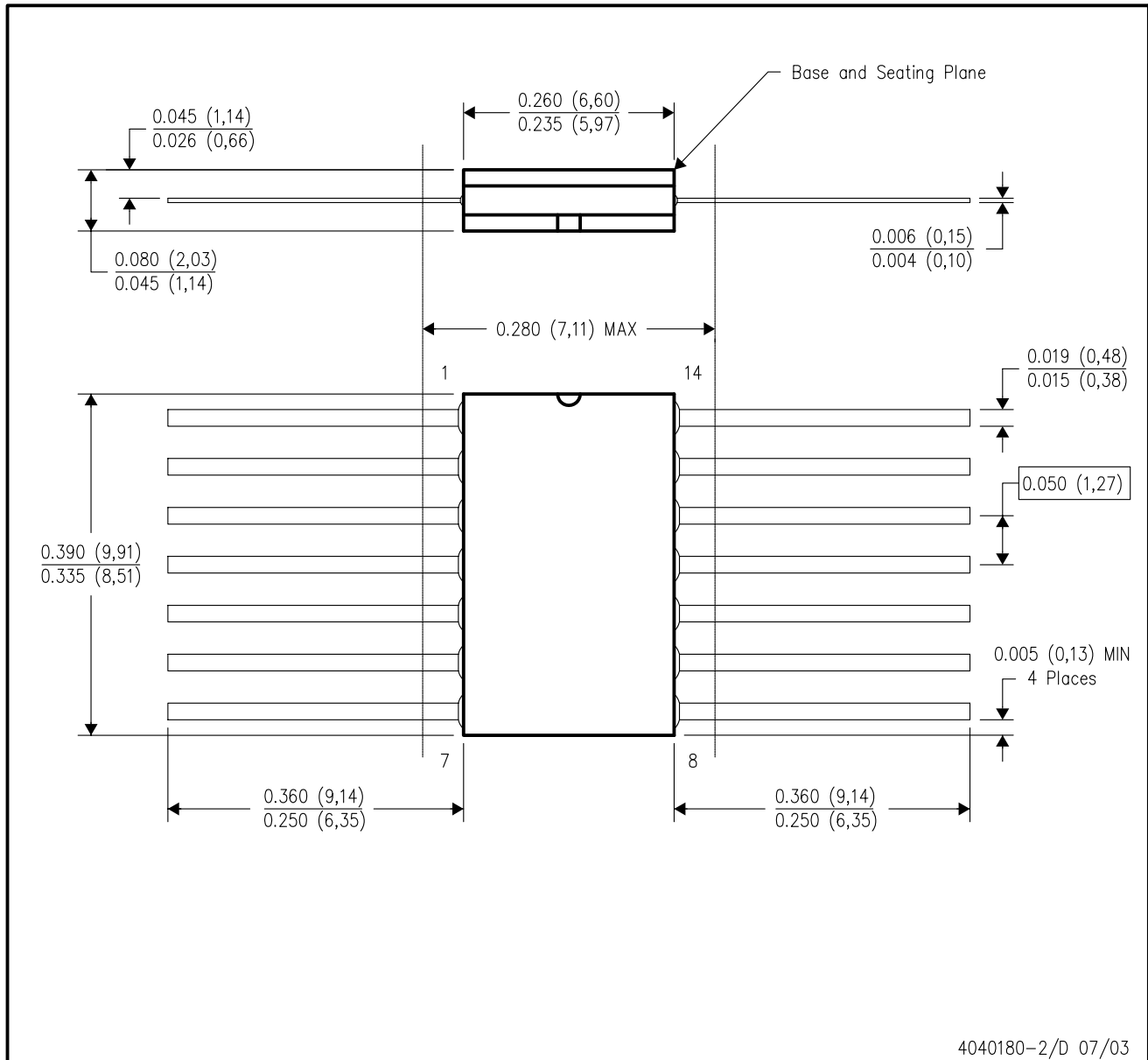


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

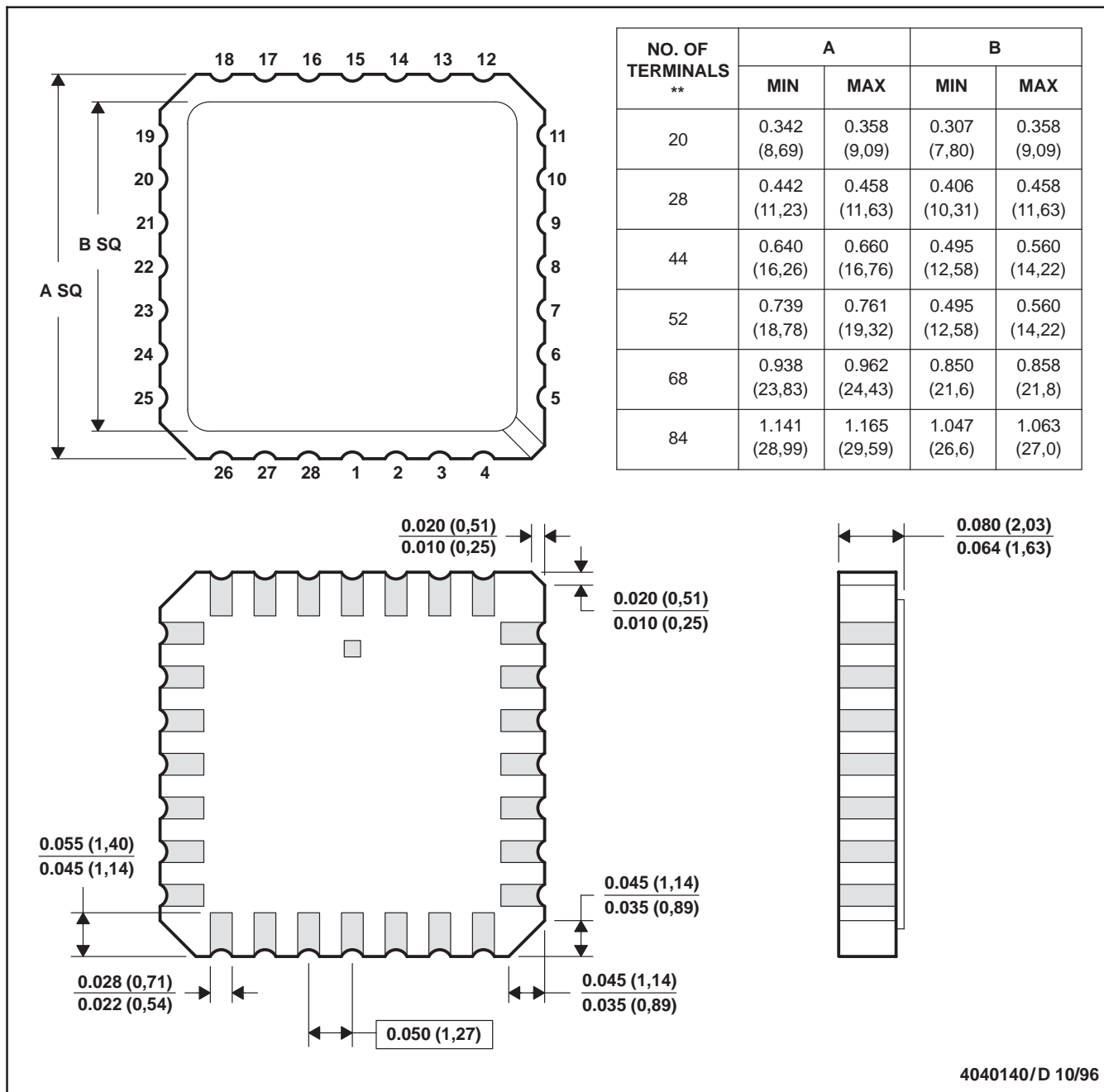


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

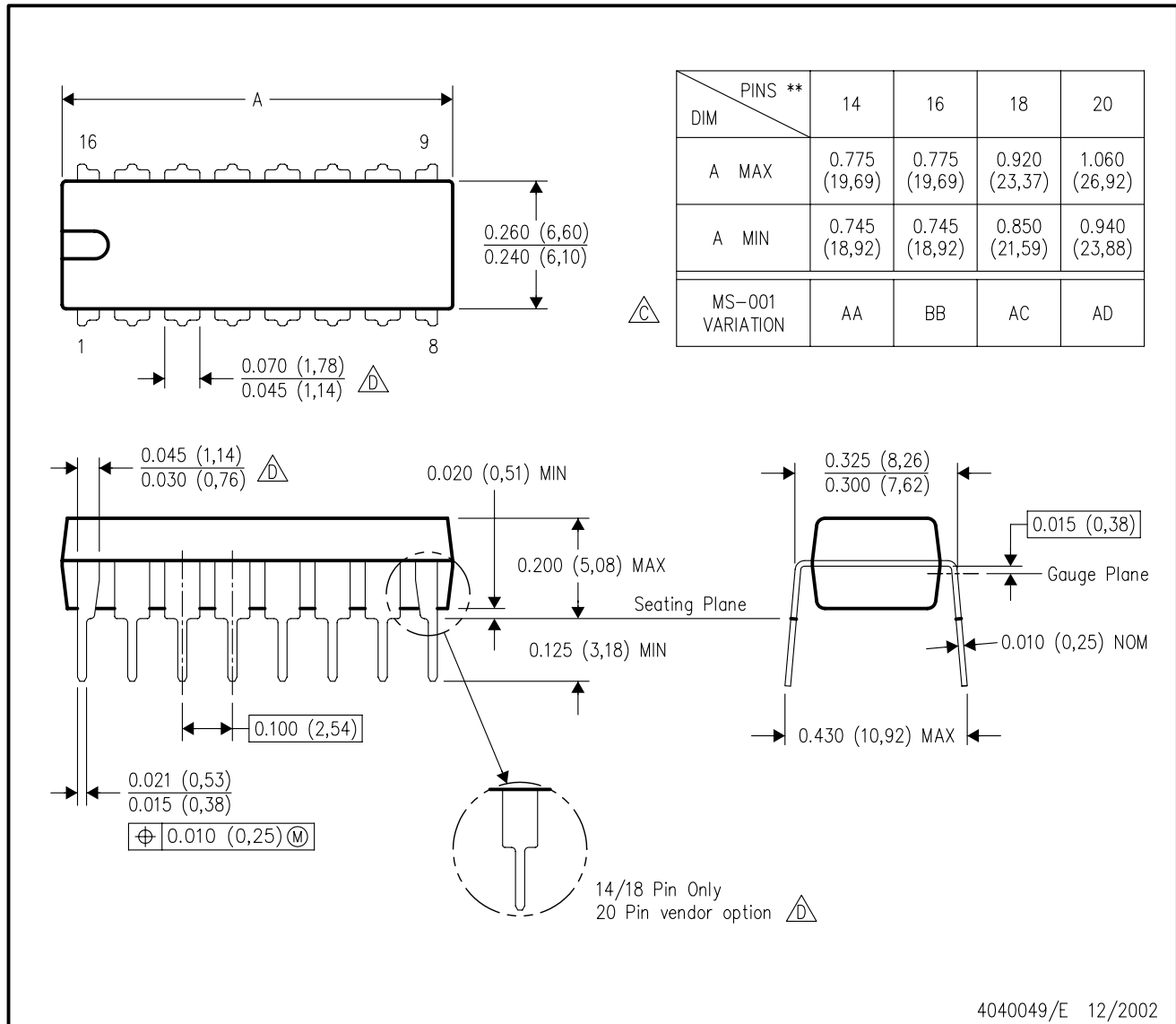


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

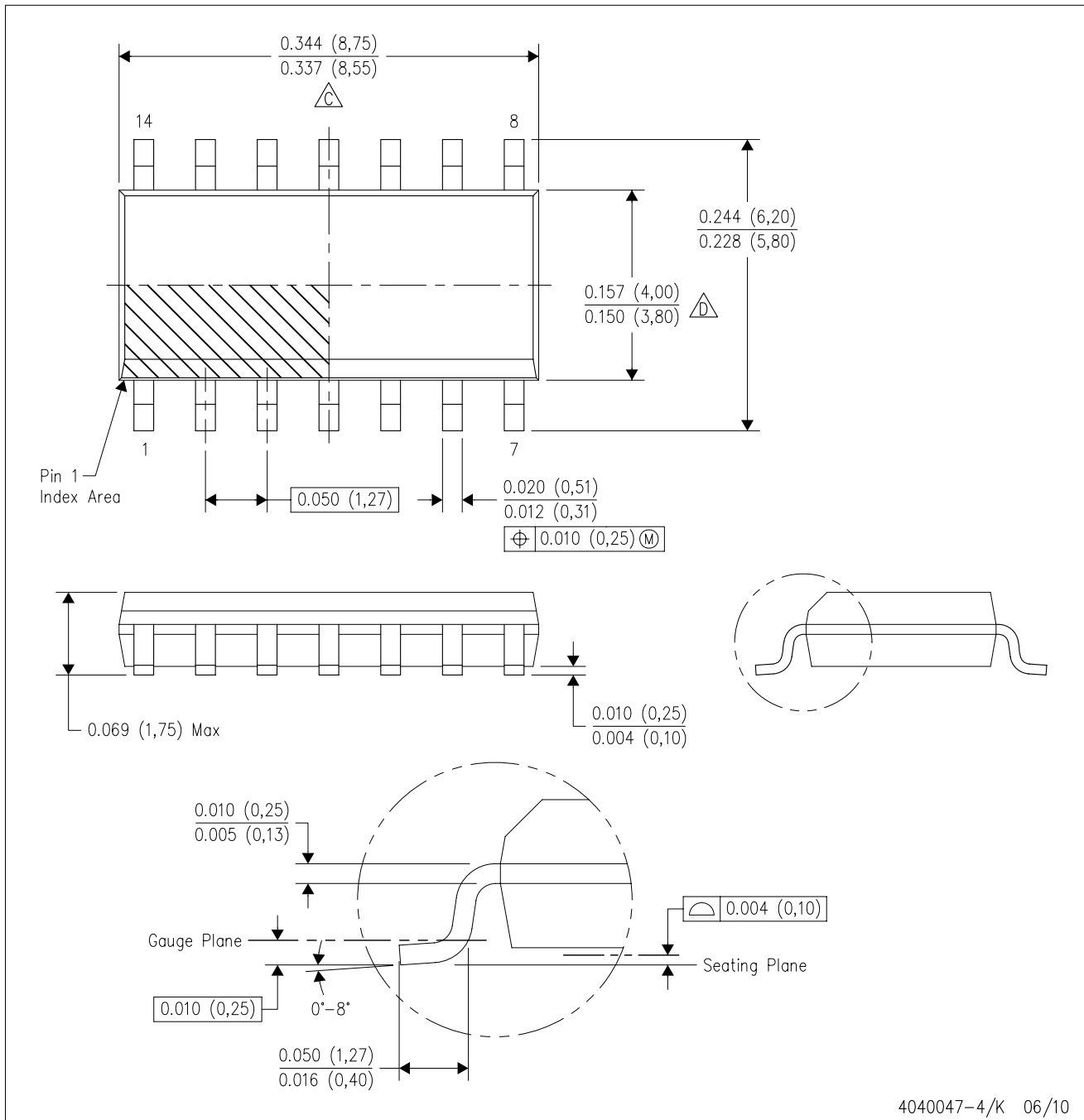


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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